

Docket No. 237457US90CONT/hc

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE



IN RE APPLICATION OF: Yasuji HIRAMATSU, et al.

SERIAL NO: 10/615,950

FILED: July 10, 2003

FOR: CERAMIC SUBSTRATE FOR SEMICONDUCTOR FABRICATING DEVICE

GAU:

EXAMINER:

INFORMATION DISCLOSURE STATEMENT UNDER 37 CFR 1.97

COMMISSIONER FOR PATENTS
ALEXANDRIA, VIRGINIA 22313

SIR:

Applicant(s) wish to disclose the following information.

REFERENCES

- The applicant(s) wish to make of record the references, some of which are cited in the attached International Search Report listed on the attached form PTO-1449. Copies of the listed references are attached, where required, as are either statements of relevancy or any readily available English translations of pertinent portions of any non-English language references.
- A check or credit card payment form is attached in the amount required under 37 CFR §1.17(p).

RELATED CASES

- Attached is a list of applicant's pending application(s) or issued patent(s) which may be related to the present application. A copy of the patent(s), together with a copy of the claims and drawings of the pending application(s) is attached along with PTO 1449.
- A check or credit card payment form is attached in the amount required under 37 CFR §1.17(p).

CERTIFICATION

- Each item of information contained in this information disclosure statement was first cited in a communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of this statement.
- No item of information contained in this information disclosure statement was cited in a communication from a foreign patent office in a counterpart foreign application or, to the knowledge of the undersigned, having made reasonable inquiry, was known to any individual designated in 37 CFR §1.56(c) more than three months prior to the filing of this statement.

DEPOSIT ACCOUNT

- Please charge any additional fees for the papers being filed herewith and for which no check or credit card payment is enclosed herewith, or credit any overpayment to deposit account number 15-0030. A duplicate copy of this sheet is enclosed.

Respectfully submitted,

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OCT 10 2003

SHEET 1 OF 1

Form PTO 1449 (Modified)		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY DOCKET NO. 237457US90CONT	SERIAL NO. 10/615,950		
		LIST OF REFERENCES CITED BY APPLICANT					
		APPLICANT		Yasuji HIRAMATSU, et al.			
		FILING DATE		July 10, 2003			
U.S. PATENT DOCUMENTS							
EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE
	AA	6,507,006	01/14/2003	Y. HIRAMATSU, et al.			
	AB	6,465,763	10/15/2000	Y. ITO, et al.			
	AC	6,475,606	11/05/2000	T. NIWA			
	AD						
	AE						
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	AG						
	AH						
	AI						
	AJ						
	AK						
	AL						
	AM						
	AN						
FOREIGN PATENT DOCUMENTS							
		DOCUMENT NUMBER	DATE	COUNTRY	TRANSLATION		
	AO	11-251040	09/17/99	JAPAN (with English Abstract)	YES	X	
	AP	9-270454	10/14/97	JAPAN (with English Abstract)	YES	X	
	AQ	9-172057	06/30/97	JAPAN (with English Abstract)	YES	X	
	AR	11-204238	07/30/99	JAPAN (with corr. EP 0 929 204)	YES	X	
	AS	0 929 204	07/14/99	EUROPE	YES		
	AT	11-273837	10/08/99	JAPAN (with English translation)	YES		
	AU	9-237826	09/09/97	JAPAN (with English translation)	YES		
	AV				YES		
OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, etc.)							
	AW						
	AX						
	AY						
	AZ	<input type="checkbox"/> Additional References sheet(s) attached					
Examiner					Date Considered		

*Examiner: Initial if reference is considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

LIST OF RELATED CASES

<u>Docket Number</u>	<u>Serial or Patent Number</u>	<u>Filing or Issue Date</u>	<u>Inventor/Applicant</u>
PER CLIENT	09/471,759	12/23/99	SAITO et al.
PER CLIENT	09/462,067	01/05/01	FURUKAWA et al.
PER CLIENT	09/787,954	03/23/01	ITO
PER CLIENT	09/787,816	03/23/01	ITO
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PER CLIENT	09/806,957	04/06/01	ITO et al.
PER CLIENT	09/926,730	04/16/01	HIRAMATSU et al.
PER CLIENT	09/890,358	07/30/01	ITO
PER CLIENT	09/958,689	10/10/01	FURUKAWA et al.
PER CLIENT	09/979,676	11/05/01	ZHOU
PER CLIENT	10/048,894	02/01/02	FURUKAWA
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PER CLIENT	09/673,953	12/21/00	ITO et al.
PER CLIENT	09/524,010	03/13/00	NIWA
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205240US0 PCT	09/807,960	05/18/01	HIRAMATSU et al.
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*Present Application; listed for information
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215240US0 PCT	09/926,362	01/16/02	HIRAMATSU et al.
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215811US0 PCT	09/926,464	01/10/02	HIRAMATSU et al.
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216926US2 PCT	10/009,174	12/10/01	HIRAMATSU et al.
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*Present Application; listed for information

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